



## Final Product Change Notification

201505002F01

**Issue Date:** 02-Nov-2015

**Effective Date:** 14-Feb-2016

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



# QUALITY

### Change Category

- |  |  |   |  |
|--|--|---|--|
| <input type="checkbox"/> Wafer Fab process   | <input type="checkbox"/> Assembly Process              | <input type="checkbox"/> Product Marking                | <input type="checkbox"/> Design                    |
| <input type="checkbox"/> Wafer Fab materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Electrical spec./Test coverage | <input type="checkbox"/> Mechanical Specification  |
| <input type="checkbox"/> Wafer Fab location  | <input type="checkbox"/> Assembly Location             | <input type="checkbox"/> Test Location                  | <input type="checkbox"/> Packing/Shipping/Labeling |

Change of bond wire from Au to Cu and release of 2nd source mold compound in SOD323F

### Details of this Change

Scheduled changes affect product types in SOD323F (SC-90) package only.

- (1) The bond wire material will be changed from gold (Au) to copper (Cu). Gold wire remains qualified for supply security reasons only.
- (2) A second source mold compound supplier will be introduced for copper wire products.

Old product: wire material is Au (with currently used mold compound suppliers)

Changed product: wire material is Cu (with currently used first and new second source mold compound supplier) or Au (with currently used mold compound suppliers)

The design and materials of all other components will remain unchanged, i.e. no change of die, die attach, and lead frame. Reliability qualification and full electrical characterization over temperature have been performed. No change on thermal behavior or mechanical dimensions. Electrical parameters remain unchanged (in specification and with the same distribution).

#### Why do we Implement this Change

- (1) Aligning with world technology standards, NXP continues to introduce copper wire for plastic SMD packages. Copper wire shows enhanced mechanical properties.
- (2) Following NXP company policy and second source material availability, a second source mold compound will be added to the BOM. The second source is already a well-established mold compound supplier for NXP GA discrete semiconductor products.

#### Identification of Affected Products

Changed products can be identified by date code after implementation.

## Product Availability

### Sample Information

Samples are available upon request  
Latest sample request date for PCN samples is 02-Dec-2015.

### Production

Planned first shipment 01-Mar-2016

## Impact

No impact to the products' functionality anticipated.

### Data Sheet Revision

No impact to existing datasheet

### Disposition of Old Products

Existing inventory will be shipped until depleted

## Related Notifications

Notification	Issue Date	Effective Date	Title
201003008F	26-Mar-2010		Change of bond wire material from gold to copper in SOT23 package
201308016F0114	14-Dec-2013	14-Mar-2014	Change of bond wire material from Au to Cu and release of 2nd source mold compound
201309012F0107	10-May-2014	05-Aug-2014	Change of bond wire from Au to Cu and release of 2nd source mold compound in SOT323

## Additional information

Affected products and sales history information: see attached file  
Self qualification: view online

## Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 02-Dec-2015.

## Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

**Name** GA Customer Support  
**e-mail address** DiscrQA.Helpdesk.GA-Products@nxp.com

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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#### Changed Orderable Part#

BZX84J-C27,115

BZX84J-C2V4,115

BZX84J-C2V7,115

BZX84J-C33,115

BZX84J-C39,115

BZX84J-C3V0,115

BZX84J-C3V3,115

BZX84J-C3V6,115

BZX84J-C3V9,115

BZX84J-C47,115

PMEG1020EJ,115

BZX84J-C4V7,115

BZX84J-C5V1,115

BZX84J-C5V6,115

PMEG2020EJ,115

PZU4.7B3,115

BZX84J-C6V2,115

BZX84J-C6V8,115

BZX84J-C7V5,115

PMEG3010EJ,115

PMEG4010EJ,115

BZX84J-B12,115

BZX84J-C8V2,115

BZX84J-C9V1,115

PMEG3002EJ,115

PMEG4002EJ,115

PESD5V0S1UJ,115

PMEG1030EJ,115

BZX84J-B18,115

BZX84J-B24,115

BZX84J-B27,115

TDZ5V6J,115

TDZ2V4J,115

TDZ2V7J,115

TDZ3V0J,115

TDZ3V3J,115  
PMEG3020EJ,115  
PMEG3005EJ,115  
BZX84J-B2V4,115  
BZX84J-B2V7,115  
BZX84J-B30,115  
BZX84J-B36,115  
TDZ3V6J,115  
TDZ3V9J,115  
TDZ4V7J,115  
TDZ5V1J,115  
TDZ6V2J,115  
PMEG3015EJ,115  
PMEG2015EJ,115  
PMEG2010AEJ,115  
BZX84J-B3V3,115  
BZX84J-B47,115  
BZX84J-B4V3,115  
TDZ10J,115  
TDZ11J,115  
TDZ12J,115  
TDZ15J,115  
PMEG3010CEJ,115  
PMEG4010CEJ,115  
BZX84J-B4V7,115  
BZX84J-B51,115  
BZX84J-B5V1,115  
BZX84J-B5V6,115  
TDZ18J,115  
TDZ27J,115  
BZX84J-B6V2,115  
BZX84J-B6V8,115  
BZX84J-B75,115  
PZU27B,115  
BZX84J-C10,115  
BZX84J-C12,115  
BZX84J-C15,115  
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BZX84J-C39,115  
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TDZ6V2J,115  
PMEG3015EJ,115  
PMEG2010AEJ,115  
BZX84J-B3V3,115  
TDZ10J,115  
TDZ11J,115  
TDZ15J,115  
PMEG3010CEJ,115  
BZX84J-B4V3,115  
BZX84J-B5V1,115  
PMEG4010CEJ,115  
BZX84J-B6V2,115  
BZX84J-B6V8,115  
BZX84J-C10,115  
BZX84J-C12,115  
BZX84J-C16,115

